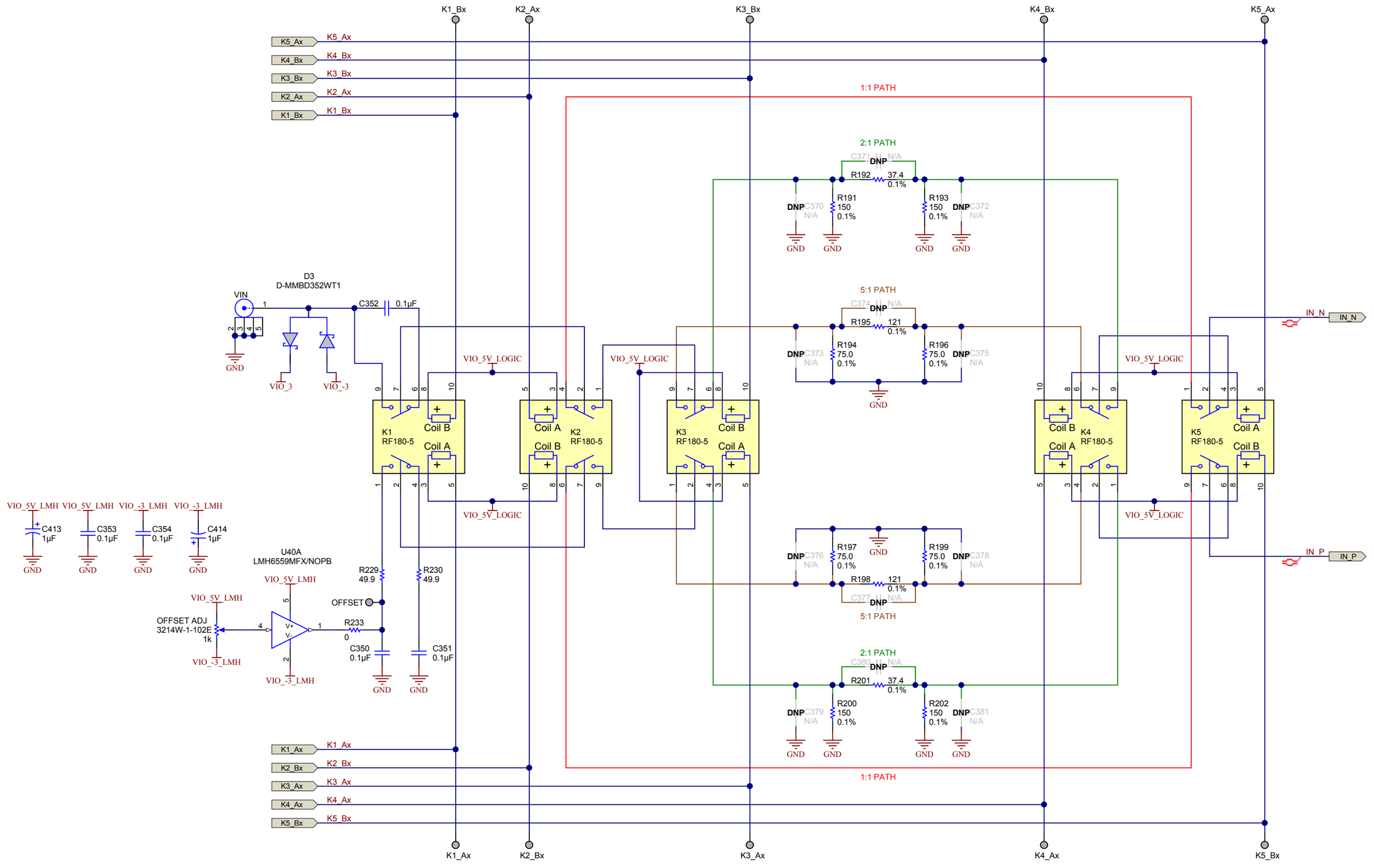

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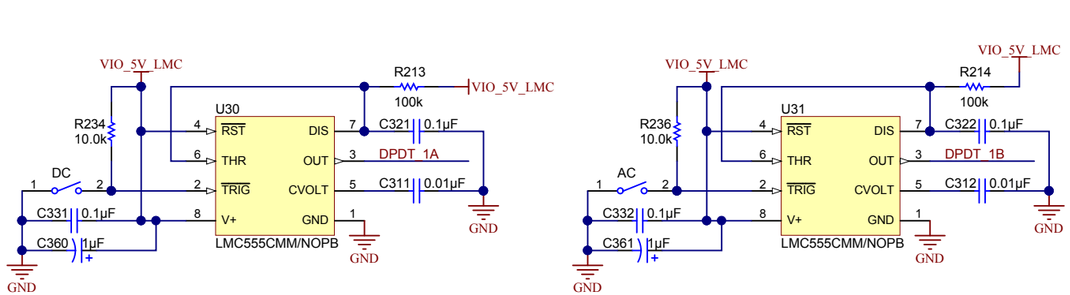
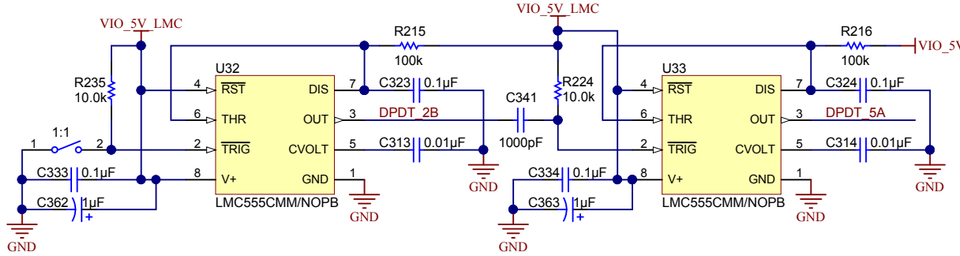
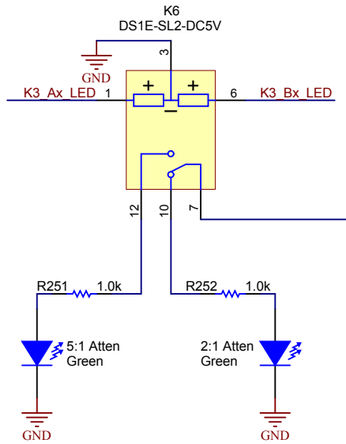
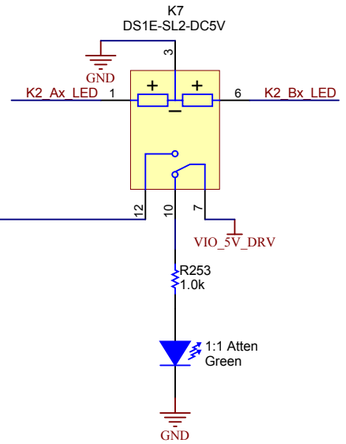
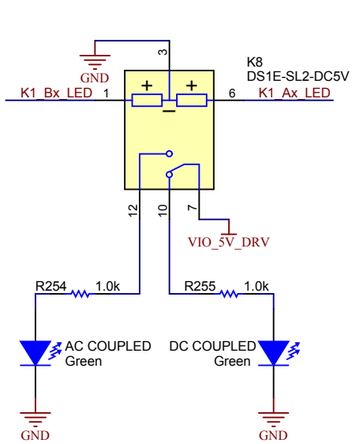
TID #: TIDA-00826		Project Title: TSW12J64EVM	
Number: 6593635	Rev: B	Sheet Title:	
SVN Rev: Version control disabled		Assembly Variant: 001	Sheet: 1 of 11
Drawn By:		File: TSW12J64EVM_B_1_FRONT_END.SchDoc	Size: B
Engineer: Enter name of project lead		Contact: http://www.ti.com/support	

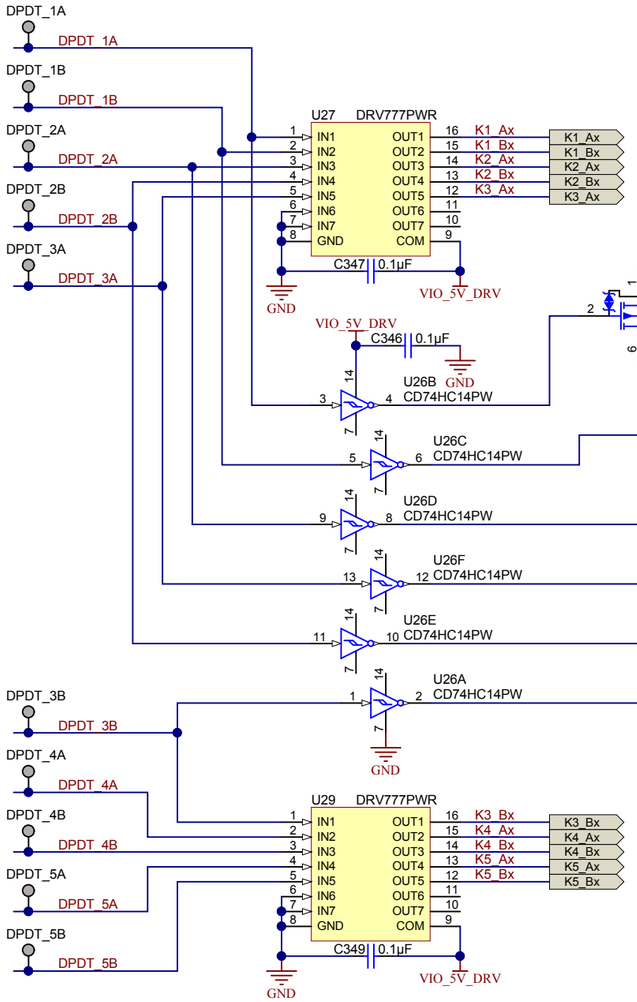


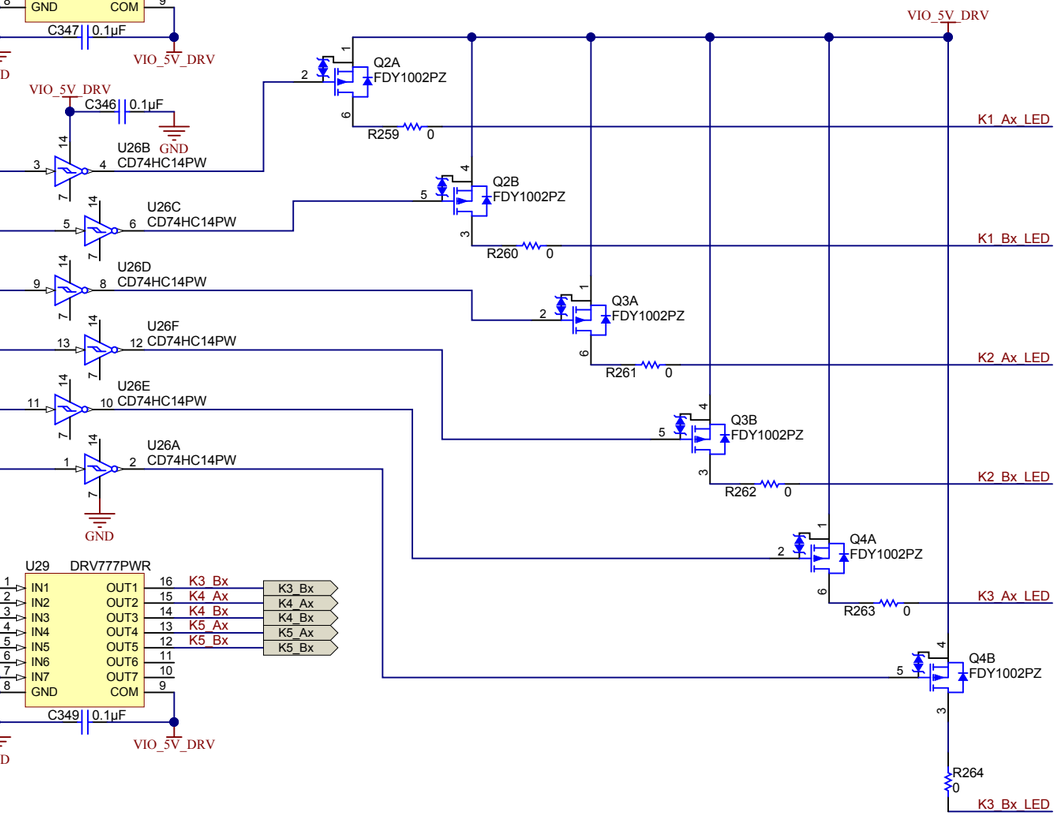


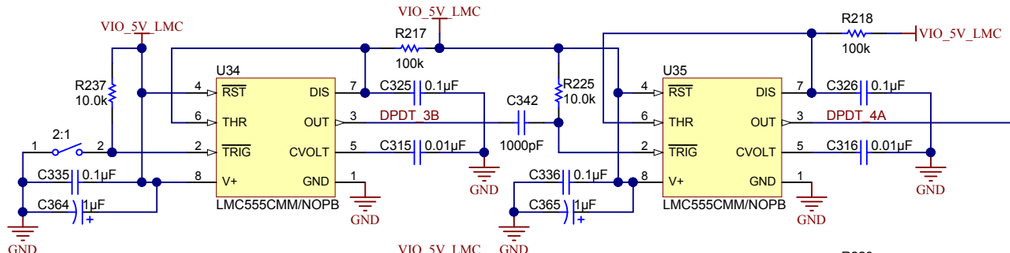


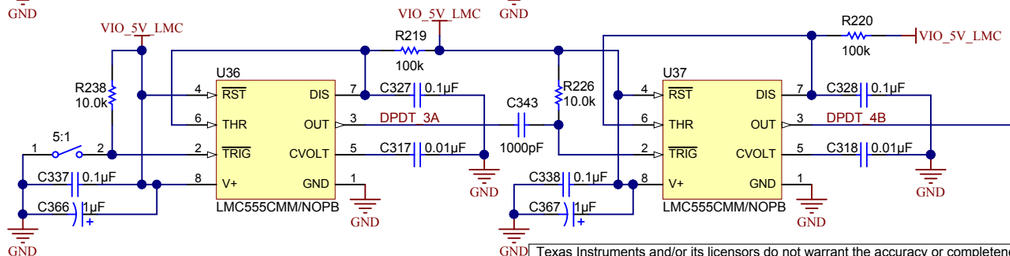


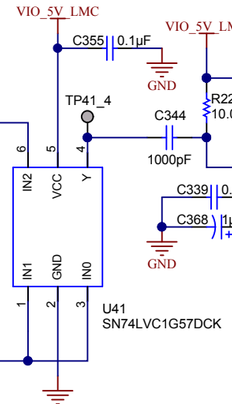


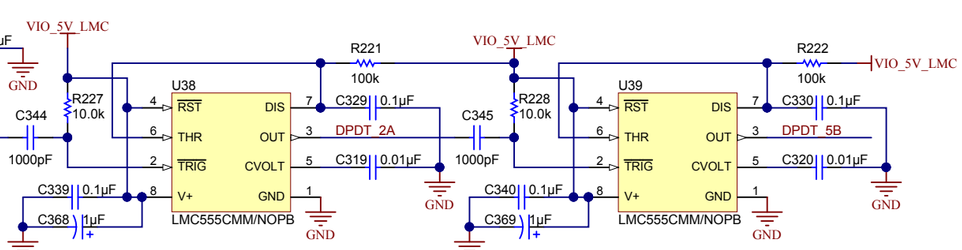












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TID #: TIDA-00826	Project Title: TSW12J64EVM	
Number: 6593635 Rev: B	Sheet Title:	
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 2 of 11
Drawn By:	File: TSW12J64EVM_B_2_RELAY_CONTROL.SchDoc	Size: B
Engineer: Enter name of project lead	Contact: http://www.ti.com/support	

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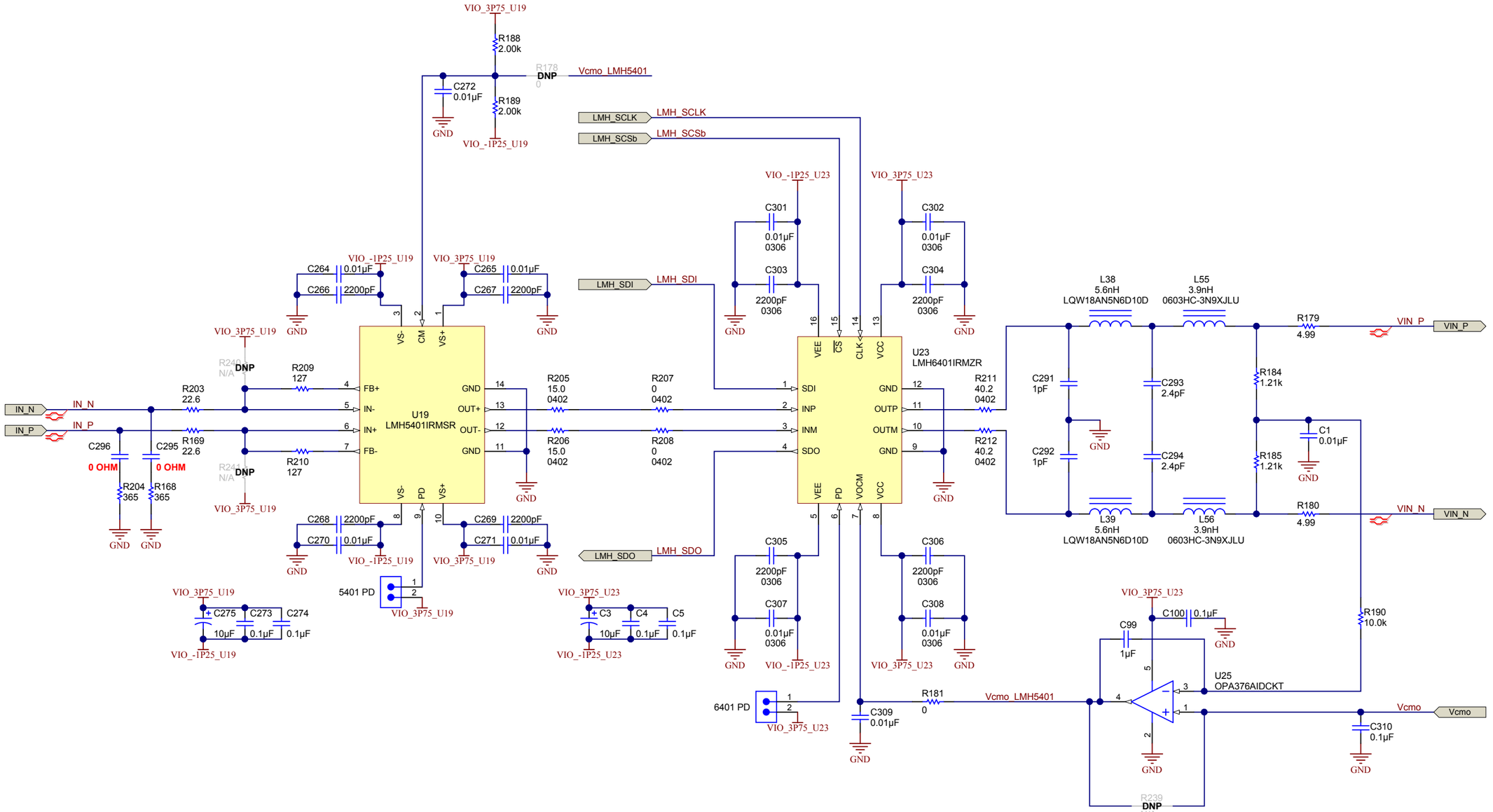

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Number: 6593635 Rev: B	Sheet Title:	
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 3 of 11
Drawn By:	File: TSW12J64EVM_B_3_ANALOG_IN.SchDoc	Size: B
Engineer: Enter name of project lead	Contact: http://www.ti.com/support	

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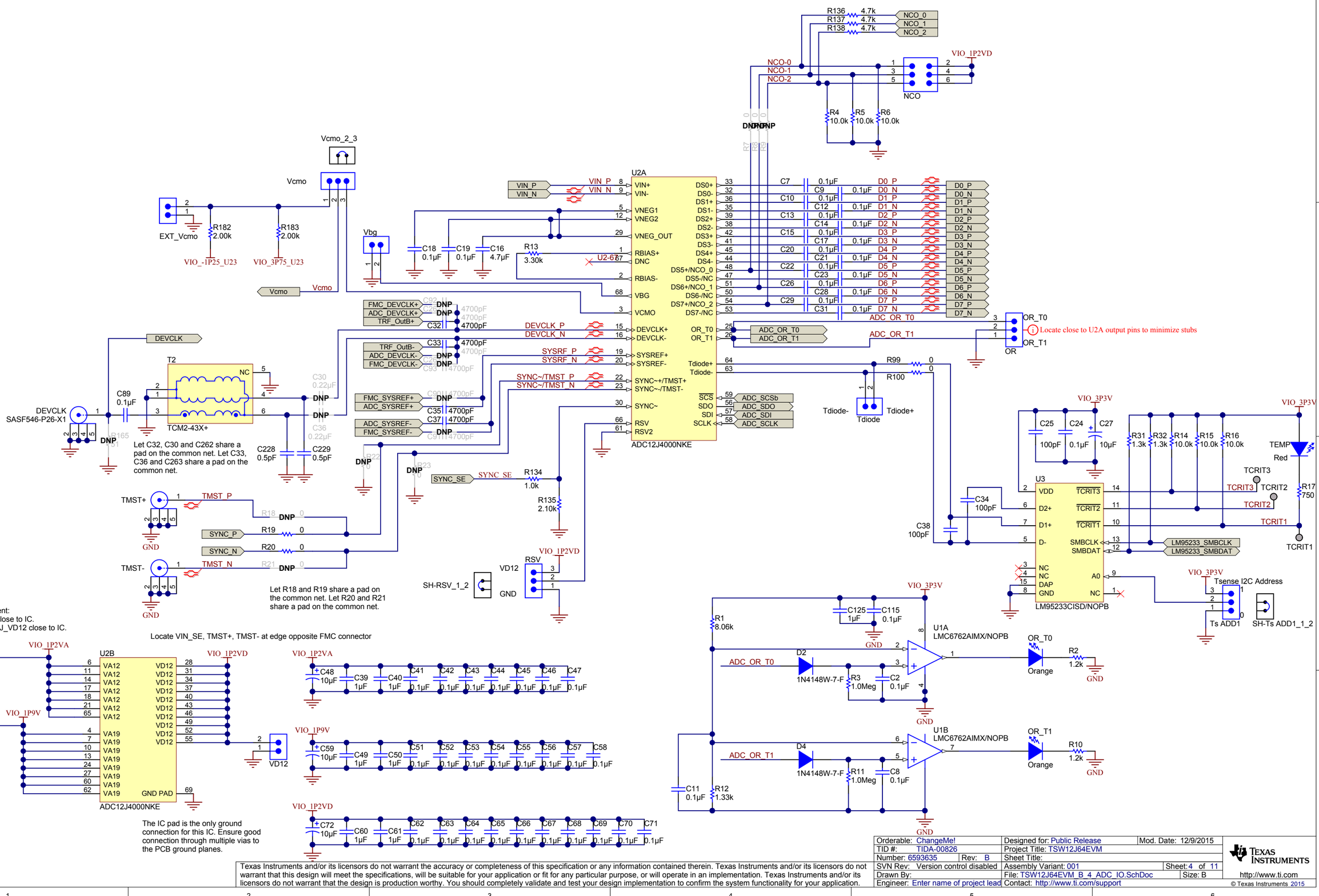

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Number: 6593635	Rev: B	Sheet Title:	
SVN Rev: Version control disabled		Assembly Variant: 001	Sheet: 4 of 11
Drawn By:		File: TSW12J64EVM_B_4_ADC_IO.SchDoc	Size: B
Engineer: Enter name of project lead		Contact: http://www.ti.com/support	

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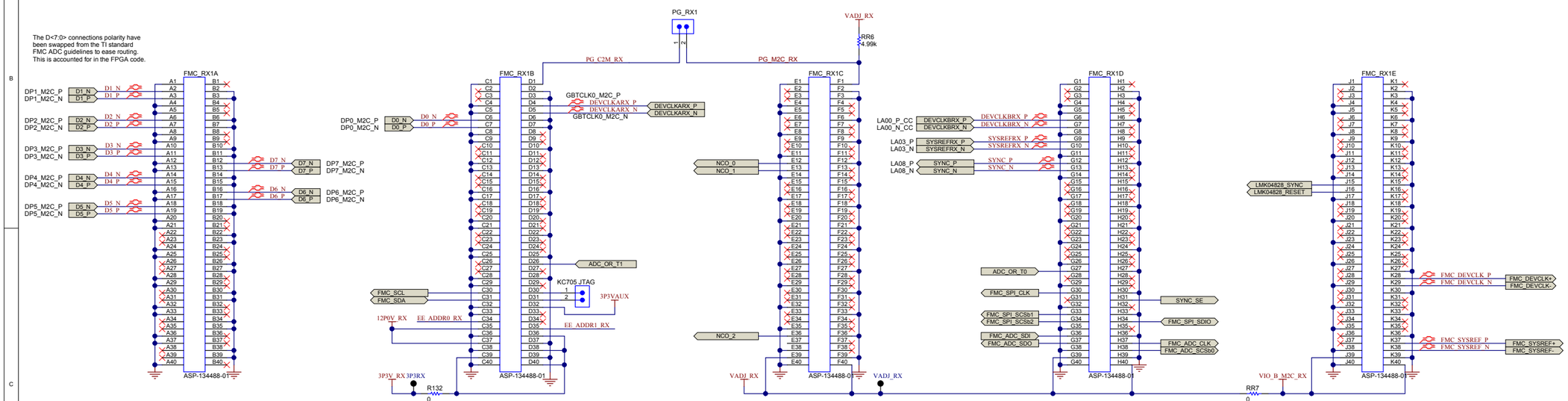
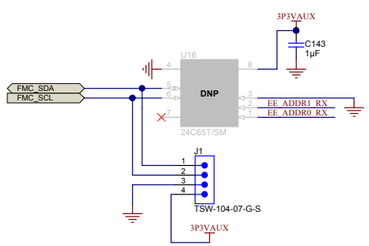
The D<7:0> connections polarity have
been swapped from the TI standard
FMC ADC guidelines to ease routing.
This is accounted for in the FPGA code.





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Number: 6593635	Rev: B	Sheet Title:	
SVN Rev: Version control disabled		Assembly Variant: 001	Sheet: 5 of 11
Drawn By:		File: TSW12J64EVM_B_5_FMC.SchDoc	Size: C
Engineer: Enter name of project lead		Contact: http://www.ti.com/support	

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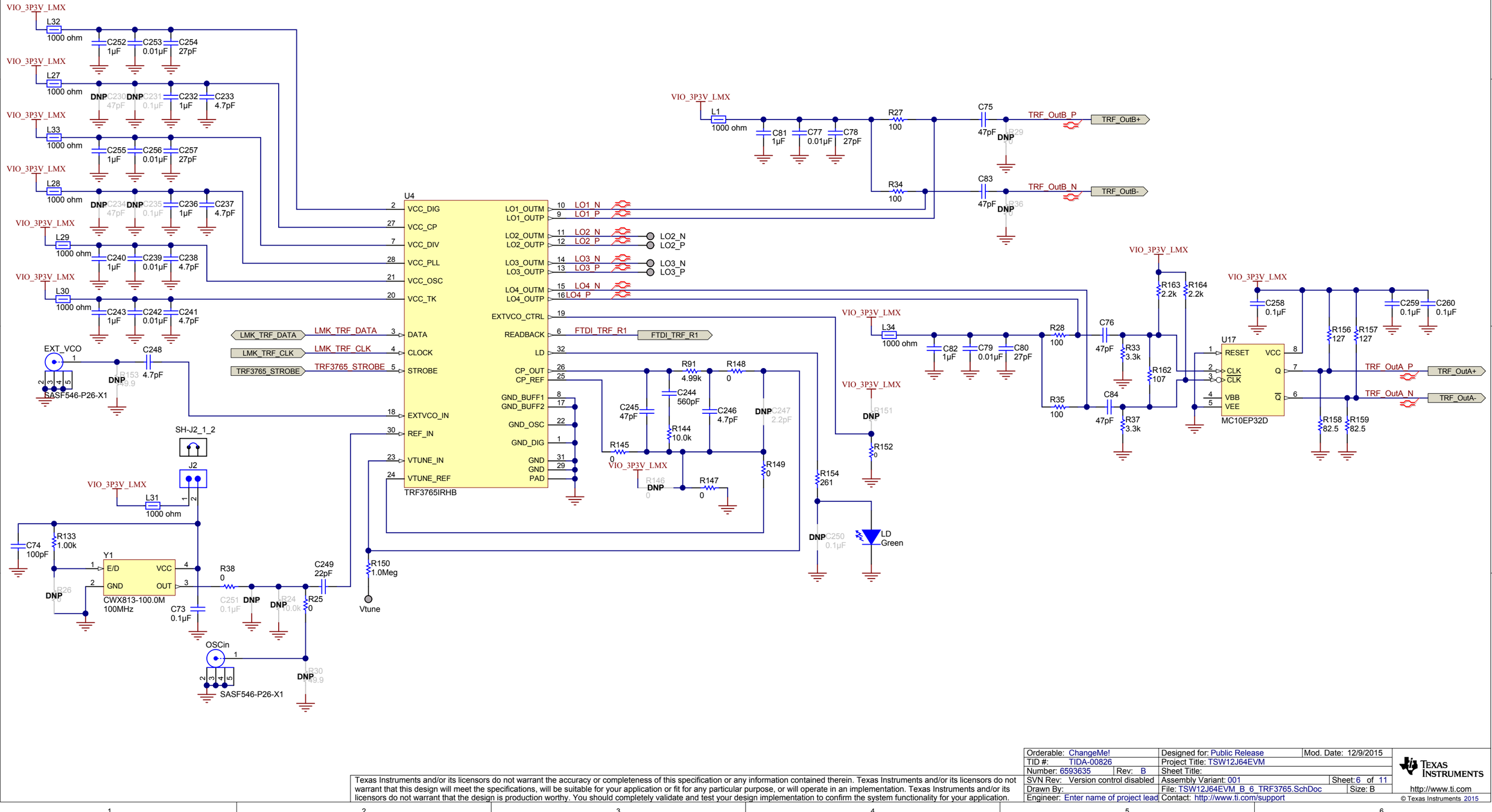

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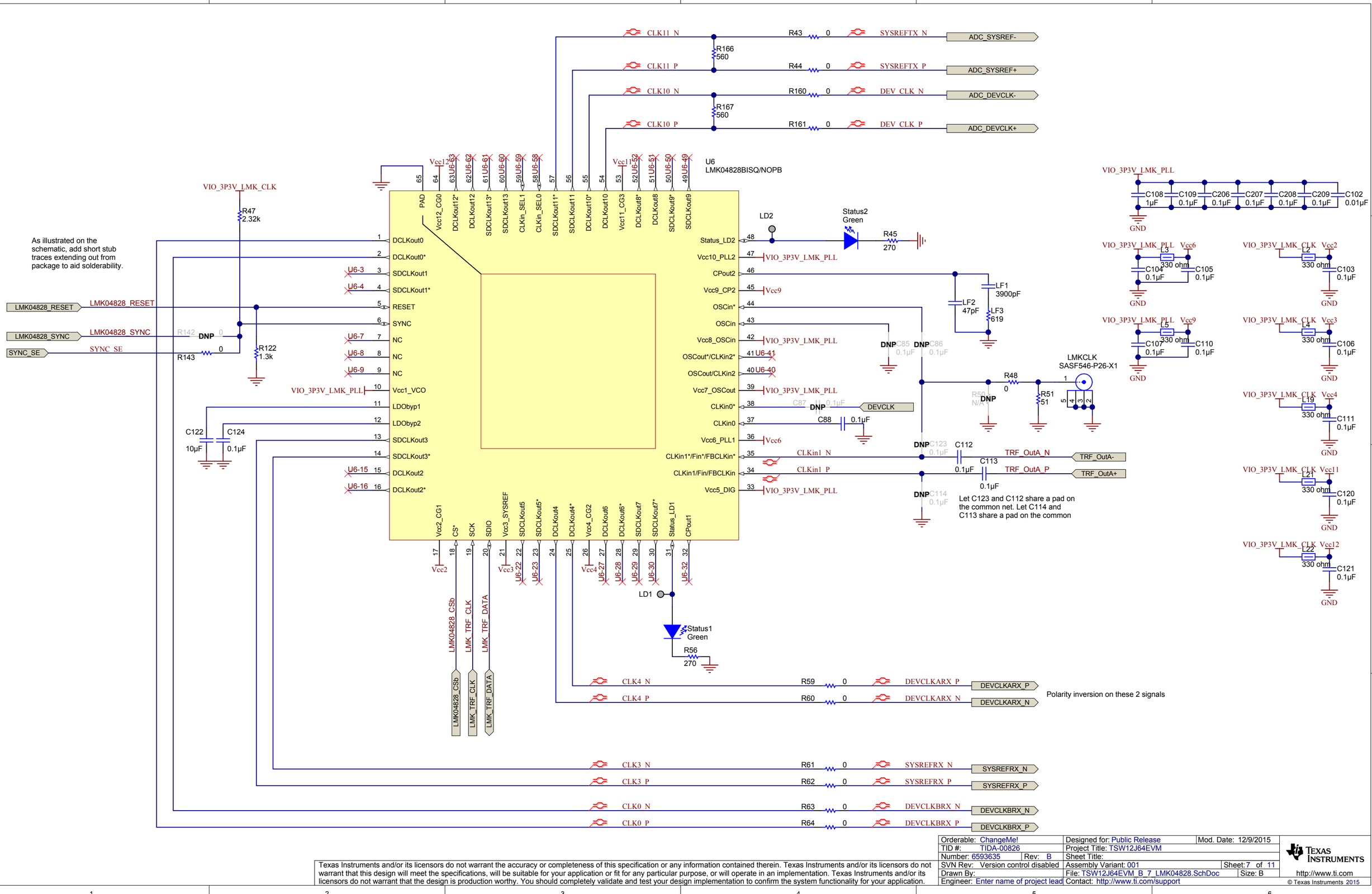

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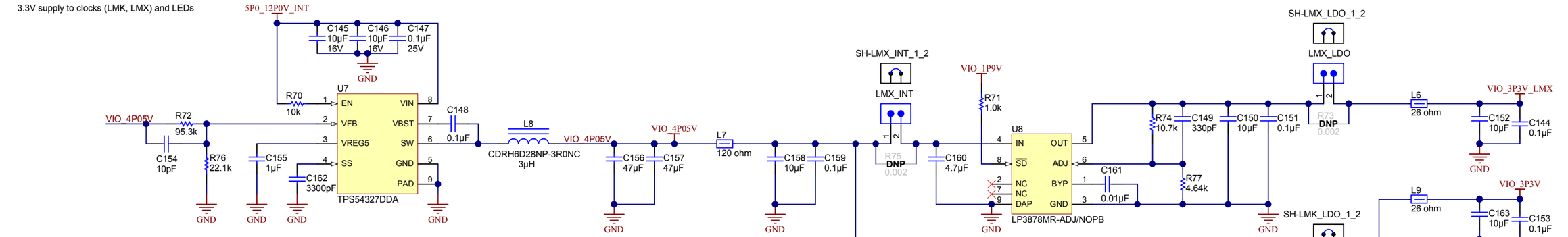
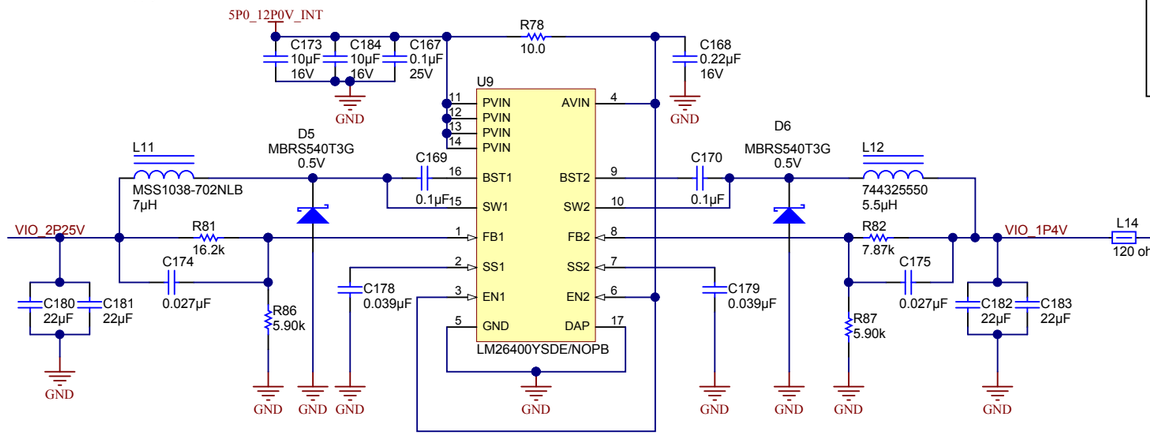
TID #: TIDA-00826	Project Title: TSW12J64EVM		
Number: 6593635 Rev: B	Sheet Title:		
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 7 of 11	
Drawn By:	File: TSW12J64EVM_B_7_LMK04828.SchDoc	Size: B	
Engineer: Enter name of project lead	Contact: http://www.ti.com/support		

3.3V supply to clocks (LMK, LMX) and LEDs

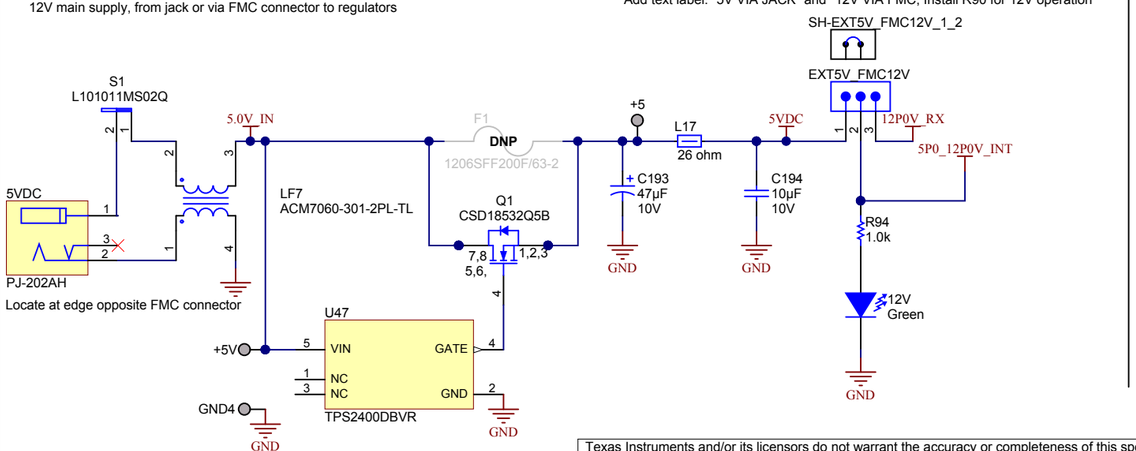


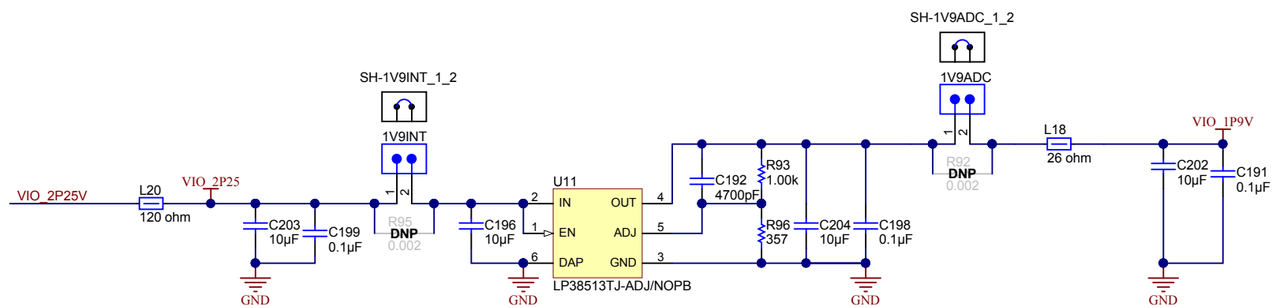
1.9V and 1.2V supply to LM15851 / ADC12JXX00



12V main supply, from jack or via FMC connector to regulators

Add text label: "5V VIA JACK" and "12V VIA FMC, Install R90 for 12V operation"





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TID #: TIDA-00826		Project Title: TSW12J64EVM	
Number: 6593635	Rev: B	Sheet Title:	
SVN Rev: Version control disabled		Assembly Variant: 001	Sheet: 8 of 11
Drawn By:		File: TSW12J64EVM_B_8_Power.SchDoc	Size: B
Engineer: Enter name of project lead		Contact: http://www.ti.com/support	

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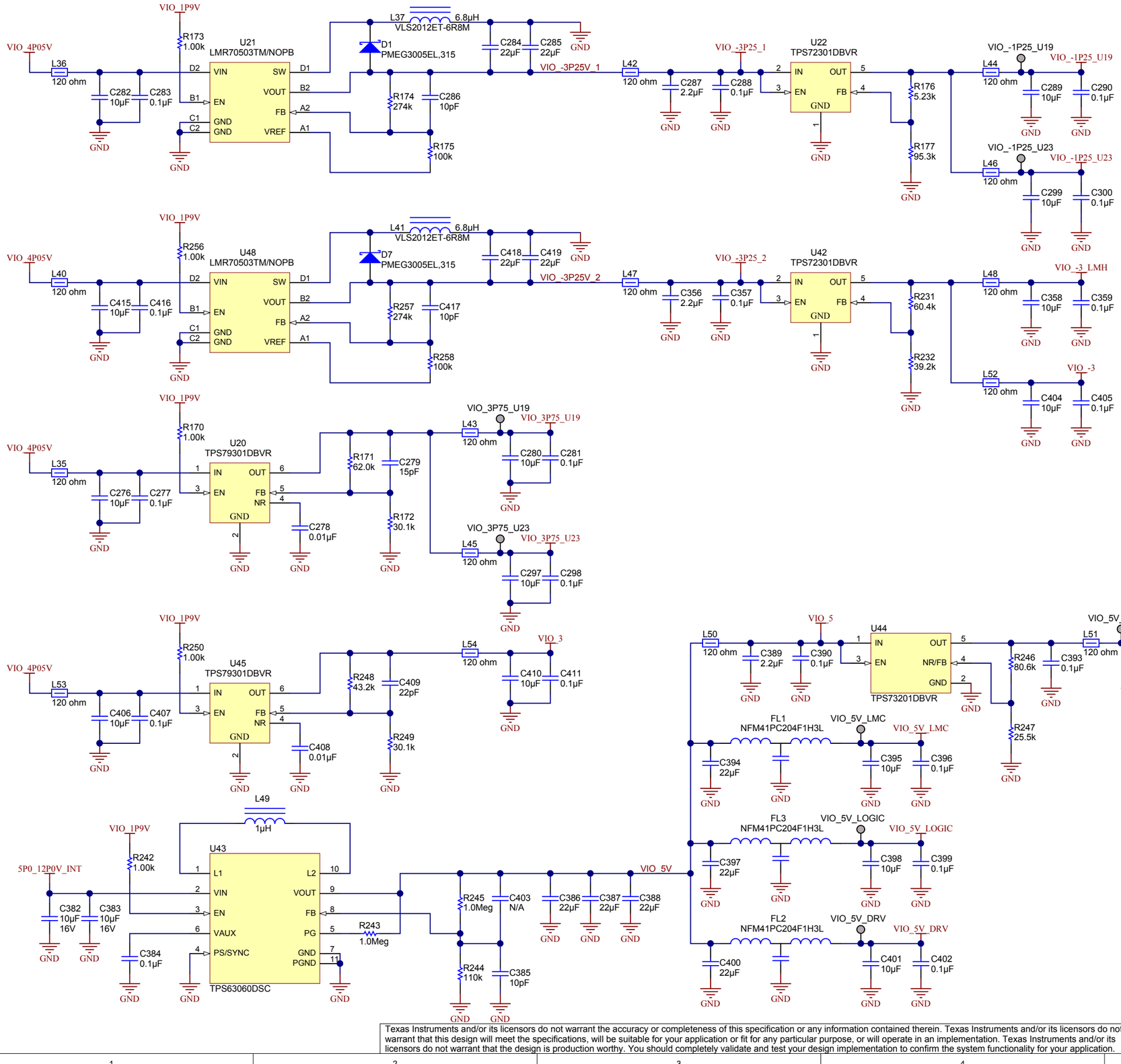

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Number: 6593635 Rev: B	Sheet Title:	
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 9 of 11
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Engineer: Enter name of project lead	Contact: http://www.ti.com/support	

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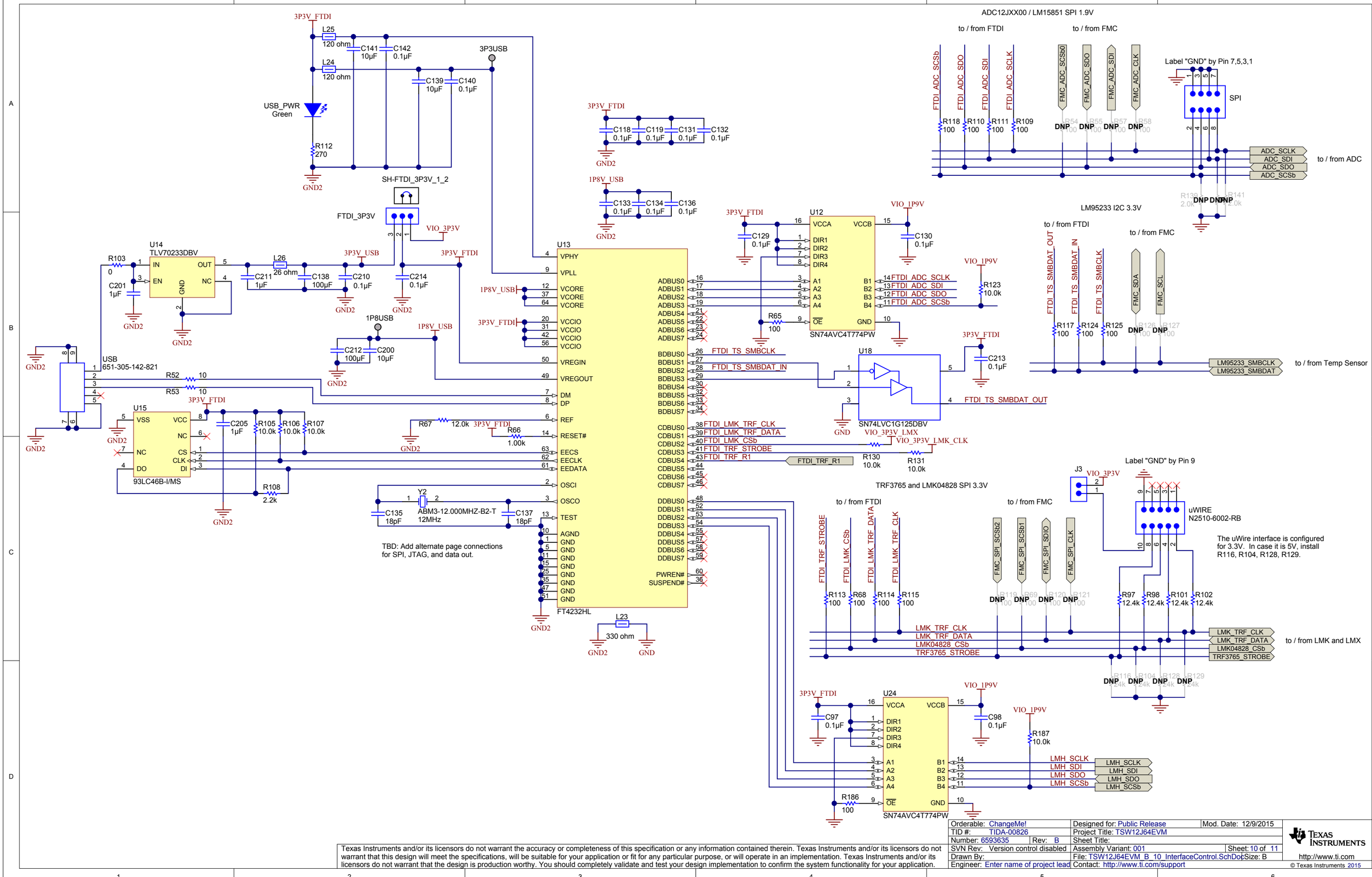

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Number: 6593635	Rev: B	Sheet Title:	
SVN Rev: Version control disabled		Assembly Variant: 001	Sheet: 10 of 11
Drawn By:		File: TSW12J64EVM_B_10_InterfaceControl.SchDoc	Size: B
Engineer: Enter name of project lead		Contact: http://www.ti.com/support	

DNP
FID1

PCB Number: 6593635
PCB Rev: B

H4
H6
1648-440-AL
NY PMS 440 0025 PH

H3
H5
1648-440-AL
NY PMS 440 0025 PH

DNP
FID2

DNP
FID3

GND GND1 GND2 GND3

Place at least two of the GND test points in the power section.

PCB
ESD LOGO
ESD Susceptible

PCB
LOGO
Pb-Free Symbol

PCB
LOGO
FCC disclaimer

PCB
LOGO
Texas Instruments

LOGO5

CAUTION HOT SURFACE

H9
MECH
FMC - FMC Screw
PMSSS 256 0075 PH

H10
MECH
FMC - FMC Nut

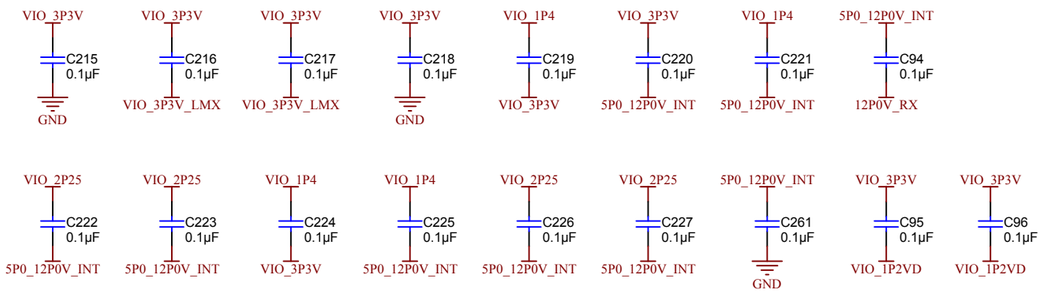
H11
MECH
FMC - FMC Screw
PMSSS 256 0075 PH

H12
MECH
FMC - FMC Nut

ZZ2
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2., unless otherwise specified.



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Number: 6593635 Rev: B	Sheet Title:	
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 11 of 11
Drawn By:	File: TSW12J64EVM_B_11_Hardware.SchDoc	Size: B
Engineer: Enter name of project lead	Contact: http://www.ti.com/support	

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